

Final Product Change Notification

Issue Date: 11-Aug-2019 Effective Date: 08-Nov-2019 Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP. For detailed information we invite you to <u>view this</u> notification online

This notice is NXP Company Proprietary.

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QUALITY

Management Summary

Microcontroller products LPC55S66JBD100 and LPC55S69JBD100 in LQFP100 package will change from version "0A" to version "1B". Changes included a die revision to resolve errata issues.

Change Category				
[]Wafer Fab Process	[] Assembly Process	[] Product Marking	[] Test Location	[X] Design
[] Wafer Fab Materials	[] Assembly Materials	[] Mechanical Specification	[]Test Process	[X] Errata
[] Wafer Fab Location	[] Assembly Location	[] Packing/Shipping/Labeling	[] Test Equipment	[] Electrical spec./Test coverage
[] Firmware	[] Other			U
LPC55S69JBD100,				
LPC55S66JBD100 Mask				
Set Revision				

Description of Change

Microcontroller products LPC55S66JBD100 and LPC55S69JBD100 in LQFP100 package will change from version "0A" to version "1B". Changes included a die revision to resolve errata issues.

Version can be recognized in product marking. There are no changes to the product datasheet.

Reason for Change

The following errata are resolved with product version "1B": - ROM.1, ROM.2, ROM.3, ROM.4, VDD.1, CMP.1, USB.1, USB.2, ADC.2, ADC.3, GPIO.1, I2S.1, AES.1, Powerqual.1, Powerqual.2. Please see errata sheet for errata details. A revised errata sheet, ES_LPC55S6x_v.1.2, is available at <u>https://www.nxp.com/docs/en/errata/ES_LPC55S6x.pdf</u>. Identification of Affected Products Top side marking

Product Availability					
Sample Information					
Samples are available upon request Production					
Planned first shipment 04-Nov-2019					
Anticipated Impact on Form, Fit, Function, Reliability or Quality					
No impact on form, fit, function, reliability or quality.					
Data Sheet Revision					
No impact to existing datasheet					
Disposition of Old Products Existing inventory will be shipped until depleted					
Additional information					
Affected products and sales history information: see attached file					
Additional documents: view online					
Timing and Logistics					
In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 10-Sep-2019.					
Contact and Support					
For all inquiries regarding the ePCN tool application or access issues, please <u>contact NXP "Global Quality</u> <u>Support Team"</u> .					
For all Quality Notification content inquiries, please contact your local NXP Sales Support team.					
For specific questions on this notice or the products affected please contact our specialist directly: Name Kirsten Rongen Position Principal Quality Engineer e-mail address kirsten.rongen@nxp.com At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.					

NXP Quality Management Team. About NXP Semiconductors

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